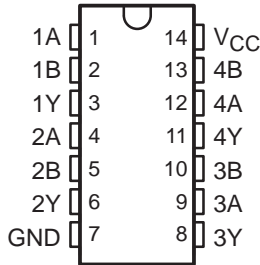


SN54HC00, SN74HC00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

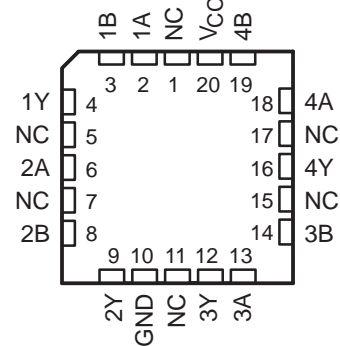
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- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20- μ A Max I_{CC}
- Typical $t_{pd} = 8$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max

SN54HC00 . . . J OR W PACKAGE
SN74HC00 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC00 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HC00 devices contain four independent 2-input NAND gates. They perform the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC00N	SN74HC00N
	SOIC – D	Tube of 50	SN74HC00D	HC00
		Reel of 2500	SN74HC00DR	
		Reel of 250	SN74HC00DT	
	SOP – NS	Reel of 2000	SN74HC00NSR	HC00
	SSOP – DB	Reel of 2000	SN74HC00DBR	HC00
	TSSOP – PW	Tube of 90	SN74HC00PW	HC00
Reel of 2000		SN74HC00PWR		
Reel of 250		SN74HC00PWT		
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC00J	SNJ54HC00J
	CFP – W	Tube of 150	SNJ54HC00W	SNJ54HC00W
	LCCC – FK	Tube of 55	SNJ54HC00FK	SNJ54HC00FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
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SN54HC00, SN74HC00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

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FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54HC00			SN74HC00			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V		1.5	1.5		V	
		$V_{CC} = 4.5$ V		3.15	3.15			
		$V_{CC} = 6$ V		4.2	4.2			
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V			0.5	0.5	V	
		$V_{CC} = 4.5$ V			1.35	1.35		
		$V_{CC} = 6$ V			1.8	1.8		
V_I	Input voltage	0		V_{CC}	0	V_{CC}	V	
V_O	Output voltage	0		V_{CC}	0	V_{CC}	V	
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 2$ V			1000	1000	ns	
		$V_{CC} = 4.5$ V			500	500		
		$V_{CC} = 6$ V			400	400		
T_A	Operating free-air temperature	-55		125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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SN54HC00, SN74HC00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC00		SN74HC00		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998		1.9		1.9	V	
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I _I	V _I = V _{CC} or 0		6 V		±0.1	±100		±1000		±1000	nA
I _{CC}	V _I = V _{CC} or 0, I _O = 0		6 V			2		40		20	μA
C _i			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC00		SN74HC00		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	2 V		45	90		135		115	ns
			4.5 V		9	18		27		23	
			6 V		8	15		23		20	
t _t		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

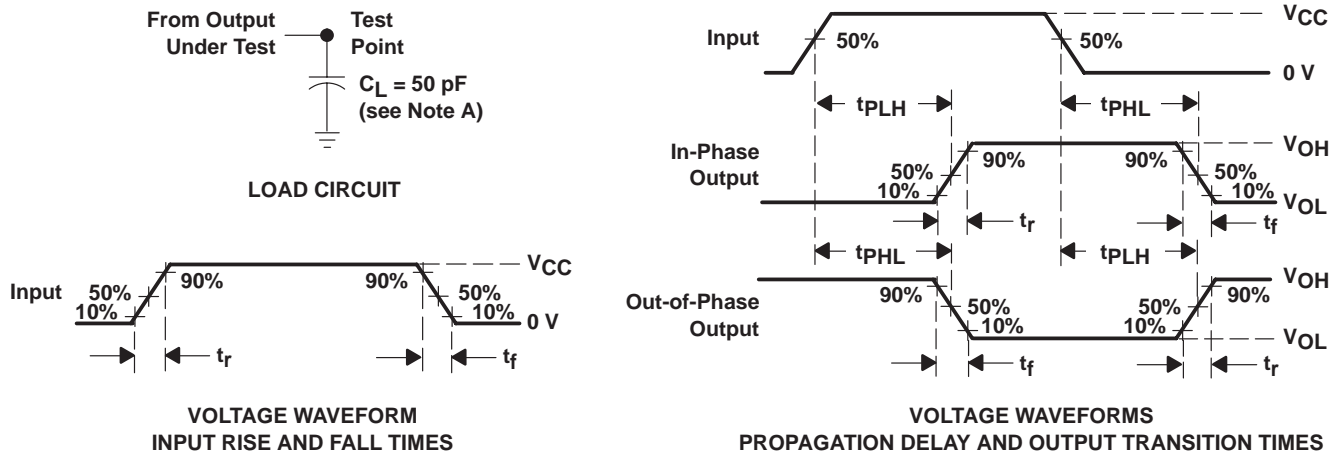
PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per gate	No load	20	pF



SN54HC00, SN74HC00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 - C. The outputs are measured one at a time with one input transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8403701VCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
5962-8403701VDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
84037012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8403701CA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
8403701DA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/65001B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/65001BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/65001BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN54HC00J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN74HC00ADBLE	OBSOLETE	SSOP	DB	14		None	Call TI	Call TI
SN74HC00D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC00DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC00DT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC00N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC00N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74HC00NS	ACTIVE	SO	NS	14		Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC00NSLE	OBSOLETE	SO	NS	14		None	Call TI	Call TI
SN74HC00NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC00PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC00PWLE	OBSOLETE	TSSOP	PW	14		None	Call TI	Call TI
SN74HC00PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC00PWT	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC00FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC00J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54HC00W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

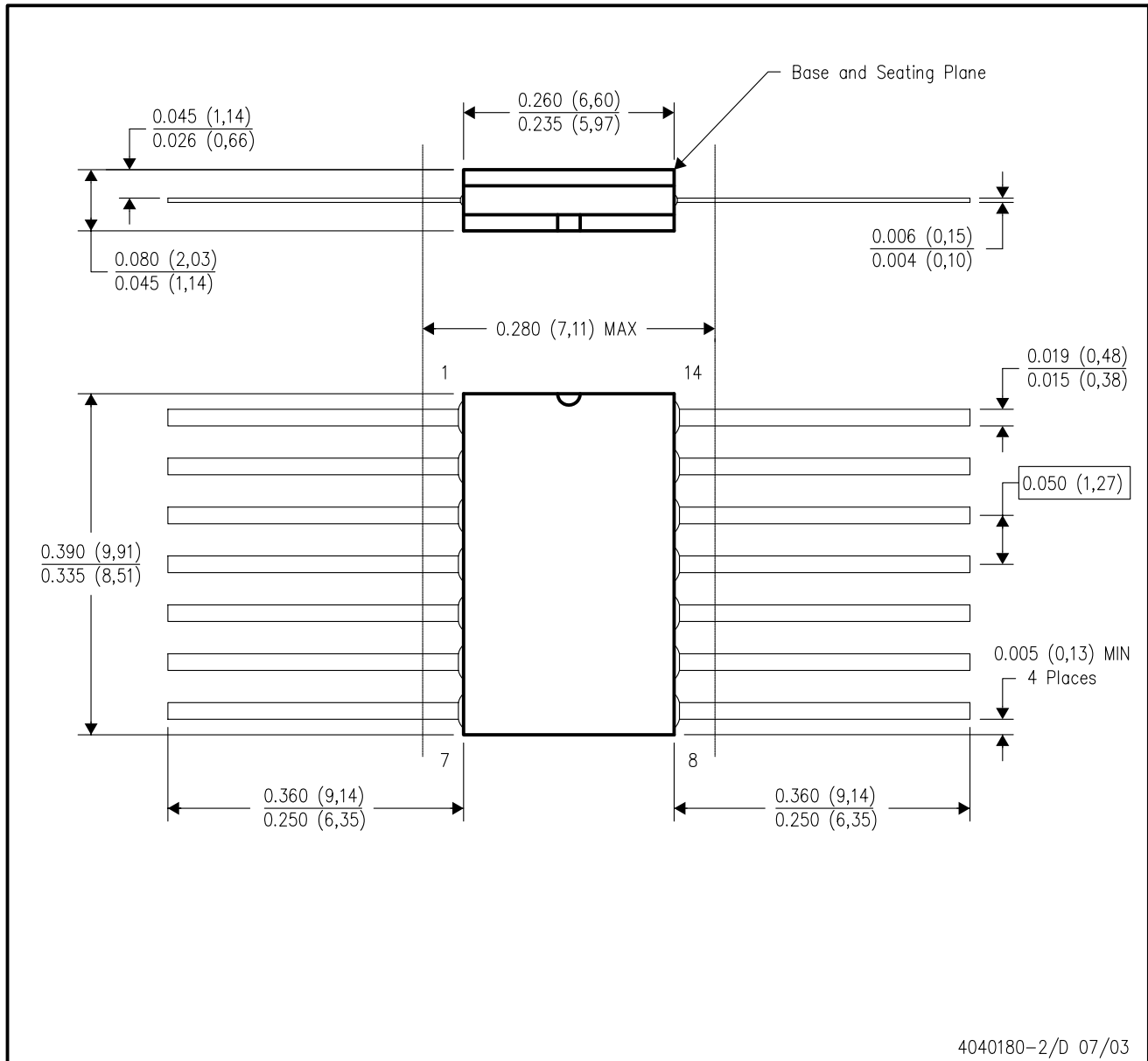


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



4040140/D 10/96

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

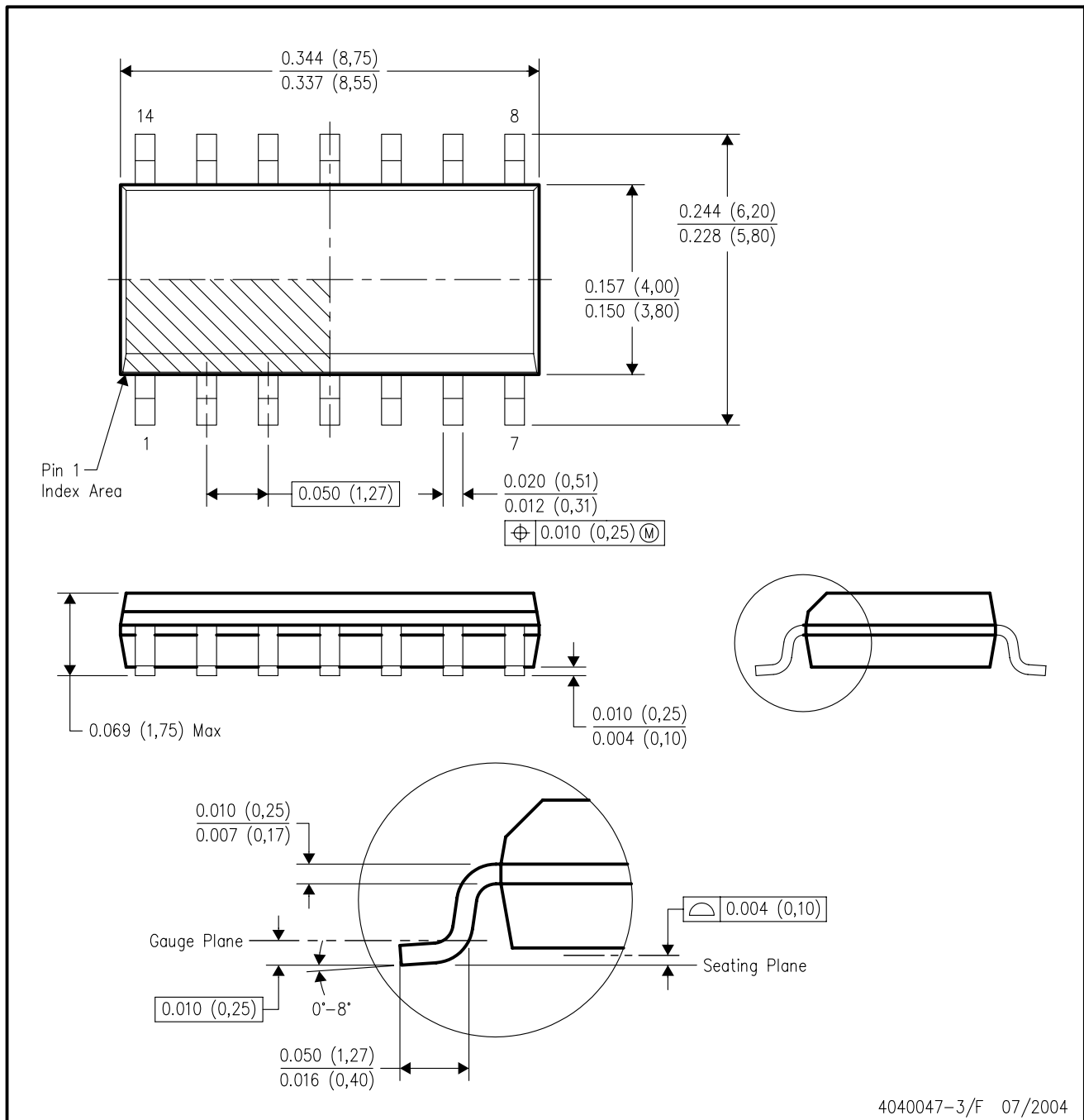
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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